

Serial No. 10/804,952
Atty. Docket MIO0048V2/40509.295

- 2 -

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AMENDMENTS TO THE CLAIMS

(The following includes a complete listing of all claims with their current status indicated.
Additional language is underscored; deletions are stricken through or double bracketed. This claim set replaces all previous versions of the claims.)

Claims 1-8. Canceled.

9. (Previously Presented) A method of fabricating a circuit board comprising:
forming a first layer of conductive material over an insulating layer;
removing portions of said conductive material of said first layer to define a first circuit pattern and a first rail area that is electrically isolated from said first circuit pattern; and,
removing portions of said conductive material of said first layer from said first rail area such that no continuous lengths of conductive material remain within said first rail area.
10. (Original) The method of claim 9, wherein said first rail area is positioned generally adjacent to a first edge of said circuit board, and spans at least a portion of the length of said first edge.
11. (Currently Amended) The method of claim 9, further comprising: A method of fabricating a circuit board comprising:
forming a first layer of conductive material over an insulating layer;
removing portions of said conductive material of said first layer to define a first circuit pattern and a first rail area that is electrically isolated from said first circuit pattern;
removing portions of said conductive material of said first layer from said first rail area such that no continuous lengths of conductive material remain within said first rail area;
removing portions of said conductive material of said first layer to define a second rail area that is electrically isolated from said first circuit pattern and said first rail area; and,
removing portions of said conductive material of said first layer from said second rail area.

Serial No. 10/804,952
Atty. Docket MIO0048V2/40509.295

- 3 -

12. (Original) The method of claim 11, wherein said second rail area is positioned generally adjacent to a second edge of said circuit board, and spans at least a portion of the length of said second edge.

13. (Original) The method of claim 11, further comprising:

forming second layer of conductive material over said insulating layer opposite said first layer;

removing portions of said conductive material of said second layer to define a second circuit pattern and a third rail area that is electrically isolated from said second circuit pattern; and,

removing portions of said conductive material of said second layer from said third rail area.

14. (Original) The method of claim 13, further comprising:

removing portions of said conductive material of said second layer to define a fourth rail area that is electrically isolated from said second circuit pattern and said third rail area; and,

removing portions of said conductive material of said second layer from said fourth rail area.

Serial No. 10/804,952
Atty. Docket MIO0048V2/40509.295

- 4 -

15. (Currently Amended) ~~The method of claim 9, further comprising:~~ A method of fabricating a circuit board comprising:

forming a first layer of conductive material over an insulating layer;
removing portions of said conductive material of said first layer to define a first circuit pattern and a first rail area that is electrically isolated from said first circuit pattern; and,
removing portions of said conductive material of said first layer from said first rail area such that no continuous lengths of conductive material remain within said first rail area;

forming second layer of conductive material over said insulating layer opposite said first layer;

removing portions of said conductive material of said second layer to define a second circuit pattern and a second rail area that is electrically isolated from said second circuit pattern; and,

removing portions of said conductive material of said second layer from said second rail area.